



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2022-05-09
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPSC20G12WLY	BF02*5G20BT7	A	998G	2022-05-09
Amount	UoM	Unit type	ST ECOPACK Grade	
5900	mg	Each	ECOPACK® 2	
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	.		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00832364	

Package Designator	Package Size	Nbr of instances	Shape
SIP	15.80 - 21 - 5	2	Through-hole
Comment	D0247 LONG LEADS		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 17th Dec 2021			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	29.717	die - leadframe	5037

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-17 Jan 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article / Homogeneous Material

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present in the component :	Tin,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	
Query	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	Response
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	
Query	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	false

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BF02*5G20817					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	5.745	mg	supplier	die	Silicium carbide	409-21-2		5.326	mg	927067	903
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.097	mg	16884	16
				supplier	metallisation	Silicon(Si)	7440-21-3		0.023	mg	4003	4
				supplier	metallisation	Copper(Cu)	7440-50-8		0.013	mg	2263	2
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.083	mg	14447	14
				supplier	metallisation	Silver(Ag)	7440-22-4		0.086	mg	14970	15
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.010	mg	1741	2
				supplier	metallisation	Vanadium(V)	7440-62-2		0.003	mg	522	1
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.016	mg	2785	3
				supplier	passivation	Silicon oxide	7631-86-9		0.025	mg	4352	4
				supplier	polymer coating	polyimide	proprietary		0.063	mg	10966	11
				supplier	alloy	Copper (Cu)	7440-50-8		3669.819	mg	990700	622003
				Leadframe	M-004 Copper and its alloys	3704.269	mg	supplier	alloy	Iron(Fe)	7439-89-6	
supplier	metallization	Nickel (Ni)	7440-02-0						29.634	mg	8000	5023
supplier	metallization	Phosphorus (P)	7723-14-0						1.112	mg	300	188
Soft solder	Solder	2.367	mg	supplier	solder	Tin(Sn)	7440-31-5		1.538	mg	649767	261
				supplier	solder	Silver(Ag)	7440-22-4		0.592	mg	250106	100
				supplier	solder	Antimony (Sb)	7440-36-0		0.237	mg	100127	40
				supplier	wire	Aluminium (Al)	7429-90-5		4.156	mg	1000000	704
Bonding wires	M-003 Aluminum and its alloys	4.156	mg	supplier	mold compound	Epoxy resin	29690-82-2		215.281	mg	100000	36488
				supplier	mold compound	Phenol resin	25068-38-6		161.461	mg	75000	27366
				supplier	mold compound	Silica	60676-86-0		1722.250	mg	800000	291907
				supplier	mold compound	Fire Retardant	Proprietary		43.056	mg	20000	7298
				supplier	mold compound	Carbon black	1333-86-4		10.764	mg	5000	1824
Encapsulation	M-011 Other inorganic materials	2152.812	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		30.651	mg	1000000	5195
				supplier	solder alloy	Tin (Sn)	7440-31-5		30.651	mg	1000000	5195
Connections coating	Solder	30.651	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		30.651	mg	1000000	5195